

ZMD31010 RBic<sub>Lite</sub><sup>™</sup> Low-Cost Sensor Signal Conditioner Technical Notes – Die Dimensions and Pad Coordinates

PRELIMINARY

## ZMD31010 RBic<sub>Lite</sub><sup>™</sup> Technical Notes Die Dimensions and Pad Coordinates

### Contents

1	RBIC <sub>LITE</sub> ™ DIE DIMENSIONS	2
2	RBIC <sub>LITE</sub> ™ PAD COORDINATES	3
3	RELATED DOCUMENTS	4

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#### 1 RBic<sub>Lite</sub><sup>™</sup> Die Dimensions

- Die size (including scribeline): 2230 µm x 1681 µm ≈ 3.75sqmm
- Core die size (without scribeline): 2080 µm x 1531 µm ≈ 3.19 sqmm
- Die thickness: 390µm
- Scribeline (distance between two core dice on wafer): 150µm
- Pads size: 68µm x 68µm



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#### 2 RBic<sub>Lite</sub><sup>™</sup> Pad Coordinates

All pads coordinates are for pad centers and related to the corner.

Name	X Coordinate in μ	Y Coordinate in $\mu$
bsink	106.3	85.9
por_n	1109.7	85.9
vbp	1210.0	85.9
vdd	1389.3	77.3
vbn	1568.1	85.9
VSS	107.2	1444.7
vssa	198.3	1444.7
vpp	356.1	1444.7
sig_pd	1428.6	1444.7
vdd	1672.3	1435.8
vgate	1809.2	1444.7

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#### **Related Documents** 3

- ZMD31010 RBic<sub>Lite</sub><sup>TM</sup> Datasheet •
- ZMD31010 RBicLite<sup>TM</sup> Development Kit Documentation •
- •
- ZMD31010 RBic<sub>Lite</sub><sup>TM</sup> Errata Sheet ZMD31010 RBic<sub>Lite</sub><sup>TM</sup> Application Notes In-Circuit Programming Boards

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